2700MHz-3100MHz, 140W, 32V High Power RF LDMOS FETs

Description

The MK3114C is a 140-watt, internally matched LDMOS FETs, designed for RF System applications with frequencies at 2700 MHz to 3100MHz.It can be used in Class AB/B and Class C for all pulsed CW formats.

• Typical Performance (on wideband board with device soldered): VDD = 32 Volts, I_{DQ} = 100 mA, Pulse Width =300us,Duty Cycle =15%.

	Freq(MHz)	G _P (dB)	P _{1dB} (W)	η _D (%)		
	2700	12.2	162	48.5%		
	2900	12.6	164	49.5%		
ĺ	3100	12.1	148	47.5%		

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift

MK3114CS
MK3114C

- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

Table 1. Maximum Ratings

Rating	Syn	nbol	Value				Unit	
DrainSource Voltage	V	DSS			65		Vdc	
GateSource Voltage	V	/ _{GS} -10 to +10			to +10	Vdc		
Operating Voltage	V	DD			+32		Vdc	
Storage Temperature Range	T؛	stg		-65	to +150		°C	
Case Operating Temperature	Т	Гc			+150		°C	
Operating Junction Temperature	Т	ΓJ			+225		°C	
Table 2. Thermal Characteristics								
Characteristic	Syn	nbol		١	/alue		Unit	
Thermal Resistance, Junction to Case								
Case Temperature 80°C, 140 W Pulsed, 32 Vdc, IDQ = 100	Rejc		0.3				°C/W	
mA								
Table 3. ESD Protection Characteristics						•		
Test Methodology					Class			
Human Body Model (per JESD22A114)		Class 2						
Table 4. Electrical Characteristics (TA = 25 C unless oth	nerwise n	oted)						
Characteristic		Symbo	bl	Min	Тур	Max	Unit	
DC Characteristics			I					
Zero Gate Voltage Drain Leakage Current						100		
(VDS = 65V, VGS = 0 V)		I _{DSS}				100	μΑ	
Zero Gate Voltage Drain Leakage Current						4		
(VDS = 32 V, VGS = 0 V)		DSS	3		1		μΑ	

Document Number: MK3114C Preliminary Datasheet V1.1

GateSource Leakage Current							
(VGS = 6 V, VDS = 0 V)	I _{GSS}			1	μΑ		
Gate Threshold Voltage	M (m)		1.0		v		
(VDS =32V, ID = 300 μA)	V _{GS} (th)		1.8		v		
Gate Quiescent Voltage			0.0		V		
(VDD = 32 V, ID = 100 mA, Measured in Functional Test)	V GS(Q)		2.3		v		
Functional Tests (On Demo Test Fixture) VDD = 32Vdc, IDQ = 100 mA, f = 3100 MHz, pulse CW, Pulse Width =300us, Duty Cycle =15%.							
Power Gain@P1dB	Gp		12.1		dB		
Drain Efficiency@P1dB	ηD		47.5		%		
1 dB Compression Point	P _{1dB}		148		W		
Input Return Loss	IRL		-7		dB		
Load Mismatch (In Innogration Test Fixture, 50 ohm system): V_{DD}	= 32 Vdc, I _{DQ} =	100 mA, f = 31	00 MHz				
VSWR 10:1 at 140W Pulsed CW Output Power No Device Degradation							

TYPICAL CHARACTERISTICS

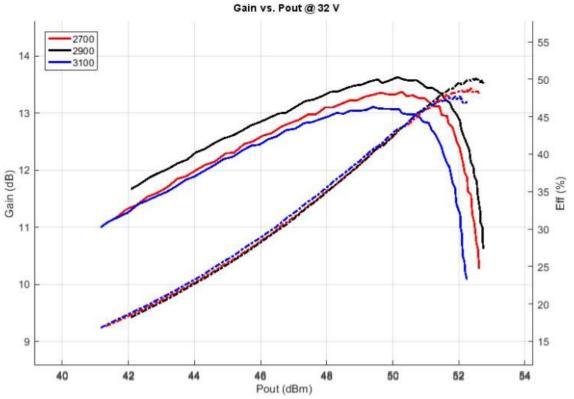
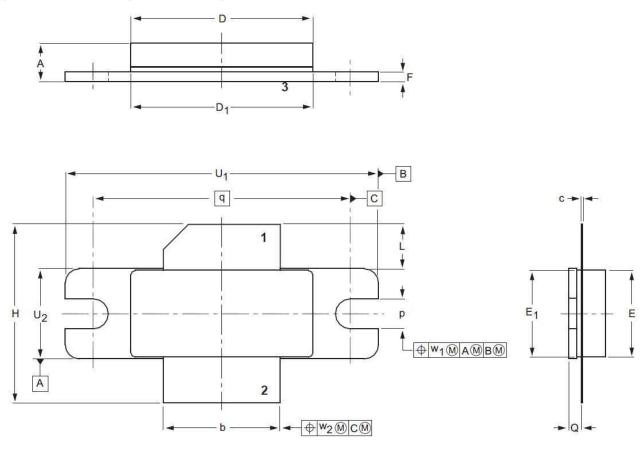


Figure 1. Power Gain and Drain Efficiency as Function of Pulse Output Power

Package Outline

Flanged ceramic package; 2 mounting holes; 2 leads

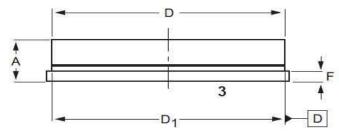


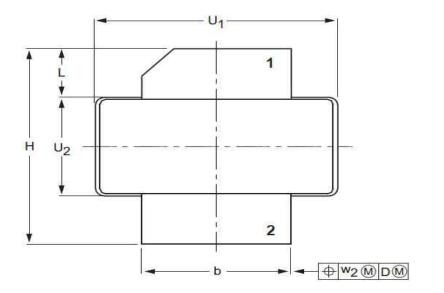
0 5 10 mm _____ scale

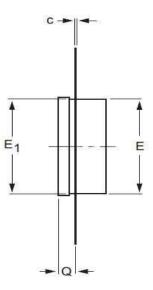
UNIT	Α	b	с	D	D1	E	E1	F	н	L	р	Q	q	U1	U ₂	W1	W ₂
mm	4.72	12.83	0.15	20.02	19.96	9.50	9.53	1.14	19.94	5.33	3.38	1.70	27.94 34.16 33.91	34.16	9.91	0.25	0.51
	3.43	12.57	0.08	19.61	19.66	9.30	9.25	0.89	18.92	4.32	3.12	1.45		33.91	9.65	0.20	0.01
inches	0.186	0.505	0.006	0.788	0.786	0.374	0.375	0.045	0.785	0.210	0.133	0.067	1.345	1.345	0.390		0.02
	0.135	0.495	0.003	0.772	0.774	0.366	0.364	0.035	0.745	0.170	0.123	0.057	1.100	1.335	0.380	0.01	0.02

OUTLINE		REFE	RENCE	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ICCCE DATE
PKG-B2E						03/12/2013

Earless flanged ceramic package; 2 leads







0 5 10 mm ______scale

UNIT	A	b	С	D	D1	E	E1	F	Н	L	Q	U1	U ₂	W ₂
mm	4.72	12.83	0.15	20.02	19.96	9.50	9.53	1.14	19.94	5.33	1.70	20.70	9.91	
											-			0.25
	3.43	12.57	0.08	19.61	19.66	9.30	9.25	0.89	18.92	4.32	1.45	20.45	9.65	
inches	0.186	0.505	0.006	0.788	0.786	0.374	0.375	0.045	0.785	0.210	0.067	0.815	0.390	0.010
	0.135	0.495	0.003	0.772	0.774	0.366	0.364	0.035	0.745	0.170	0.057	0.805	0.380	0.010

OUTLINE		REFER	RENCE	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	
PKG-B2						03/12/2013

Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2017/10/19	Rev 1.0	Preliminary Datasheet Creation
2022/5/10	Rev 1.1	Modification on 1 st page, and Rj etc

Disclaimers

Specifications are subject to change without notice. Innogration believes the information contained within this data sheet to be accurate and reliable. However, no responsibility is assumed by Innogration for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Innogration . Innogration makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. "Typical" parameters are the average values expected by Innogration in large quantities and are provided for information purposes only. These values can and do vary in different applications and actual performance can vary over time. All operating parameters should be validated by customer's technical experts for each application. Innogration products are not designed, intended or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Innogration product could result in personal injury or death or in applications for planning, construction, maintenance or direct operation of a nuclear facility. For any concerns or questions related to terms or conditions, pls check with Innogration and authorized distributors Copyright © by Innogration (Suzhou) Co.,Ltd.